Traditional High Q (>10,000) Low ESR Multi-Layer Ceramic Capacitors

1111C/P (0.110” x 0.110”)

Product Features

- High Q
- High Power
- Low ESR/ESL
- Low Noise
- High Self-Resonance
- Ultra Stable Performance
- Capacitance Range: 0.1pF to 10000pF
- Working Voltage: 500V
- Extended Voltage: 1500V

Product Applications

Typical Functional Applications

• Tuning • Bypass • Coupling
• Feedback • D.C. Blocking
• Impedance Matching

Typical Circuit Applications

• UHF/Microwave RF Power Amplifiers
• Mixers • Oscillators • Filter Networks
• Low Noise Amplifiers • Timing Circuits and Delay Lines

Marking shown for illustration purposes only. Actual marking may differ.

Part Numbering

1111	C	100	J	W	501	X	TV
Case Size (.110” x .110”)	C=NP0 P=P90	Capacitor Code 100=10x10⁰=10pF 1R0=1.0pF	Capacitance Tolerance *See Table*	Termination Type *See Table*	Rated Voltage *See Table*	Laser Marking	Add TV for Vertical Orientation

Capacitance Tolerance Codes

Code	A	B	C	D	F	G	J	K
Tol.	±0.05pF	±0.1pF	±0.25pF	±0.5pF	±1%	±2%	±5%	±10%

Voltage Codes

Voltage	Code
50V	500
100V	101
200V	201
300V	301
500V	501
600V	601
1000V	102
1500V	152

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1111C/P Capacitance Values

- **NP0=C; P90=P**
- **Maximum Capacitance: 1111P=1000pF; 1111C=10000pF**
- ** - Available in NP0 only.*

Special capacitances, tolerances and WVDC are available. Please contact PPI.

Marking shown for illustration purposes only. Actual marking may differ.

Cap. pF	Cap Code	Tol.	Rated WVDC Std.	Rated WVDC Ext.	Cap. pF	Cap Code	Tol.	Rated WVDC Std.	Rated WVDC Ext.	Cap. pF	Cap Code	Tol.	Rated WVDC Std.	Rated WVDC Ext.	Cap. pF	Cap Code	Tol.	Rated WVDC Std.	Rated WVDC Ext.
0.1	0R1	A,B	500V	1000V or 1500V	3.3	3R3	A,B C,D	500V	1000V or 1500V	36	360	F,G, J,K	500V	1000V or 1500V	390	391	F,G, J,K	200V	600V
0.2	0R2				3.6	3R6				39	390				430	431			
0.3	0R3				3.9	3R9				43	430				470	471			
0.4	0R4				4.3	4R3				47	470				510	511	F,G, J,K	100V	200V
0.5	0R5	A,B, C,D	500V	1000V or 1500V	4.7	4R7				51	510				560	561			
0.6	0R6				5.1	5R1				56	560				620	621			
0.7	0R7				5.6	5R6				62	620				680	681			
0.8	0R8				6.2	6R2				68	680				750	751			
0.9	0R9				6.8	6R8				75	750				820	821			
1.0	1R0				7.5	7R5				82	820				910	911			
1.1	1R1				8.2	8R2				91	910				1000	102			
1.2	1R2				9.1	9R1				100	101				1100	112*	F,G, J,K	200V	N/A
1.3	1R3				10	100	F,G, J,K	500V	1000V or 1500V	110	111	F,G, J,K	300V	1000V	1200	122*			
1.4	1R4				11	110				120	121				1500	152*			
1.5	1R5				12	120				130	131				1800	182*			
1.6	1R6				13	130				150	151				2200	222*	F,G, J,K	100V	N/A
1.7	1R7				15	150				160	161				2700	272*			
1.8	1R8				16	160				180	181				3000	302*			
1.9	1R9				18	180				200	201				3300	332*			
2.0	2R0				20	200				220	221	F,G, J,K	200V	600V	4700	472*			
2.1	2R1				22	220				240	241				5100	512*			
2.2	2R2				24	240				270	271				5600	562*	F,G, J,K	50V	N/A
2.4	2R4				27	270				300	301				10000	103*			
2.7	2R7				30	300				330	331								
3.0	3R0				33	330				360	361								

*Available in NP0 only

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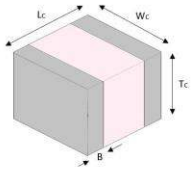
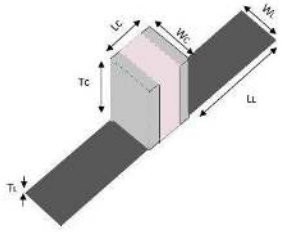
Terminations Types and Codes



Chip Termination:
Codes: **W, L, P**



Microstrip Termination:
Codes: **MS, MN**

Magnetic Terminations	
Termination Code	**Termination**
W RoHS	100% Sn Solder over Nickel Plating
L	90% Sn10%Pb Tin/Lead Solder over Nickel Plating
MS RoHS	100% Silver
Non-Magnetic Terminations	
P RoHS	100%Sn Solder over Copper Plating
MN RoHS	100% Silver

Capacitor Dimensions

Unit: inch (millimeter)

Magnetic Terminations

		Capacitor Dimensions				Lead Dimensions		
Code	**Term.**	**Length**	**Width**	**Thickness**	**Overlap**	**Length**	**Width**	**Thickness**
		Lc	**Wc**	**Tc**	**B**	**LL**	**WL**	**TL**
W/L	Chip	0.110 + 0.020 to -0.010 (2.79 +0.51 to -0.25)	0.110 ± 0.010 (2.79 ±0.25)	0.10 (2.54 max)	0.024 (0.60max)	-	-	-
MS	Microstrip	0.135 ± 0.015 (3.43 ± 0.38)	0.110 ± 0.010 (2.79 ±0.25)	0.10 (2.54 max)	-	0.250 (6.35) min	0.093 ±0.005 (2.36 ± 0.13)	0.004 ± 0.001 (0.10 ± 0.13)

Non-Magnetic Terminations

Code	**Term.**	**Length**	**Width**	**Thickness**	**Overlap**	**Length**	**Width**	**Thickness**
		Lc	**Wc**	**Tc**	**B**	**LL**	**WL**	**TL**
P	Chip	0.110 + 0.020 to -0.010 (2.79 +0.51 to -0.25)	0.110 ± 0.010 (2.79 ±0.25)	0.10 (2.54 max)	0.024 (0.60max)	-	-	-
MN	Microstrip Non-Magnetic	0.135 ± 0.015 (3.43 ± 0.38)	0.110 ±0 .010 (2.79 ±0.25)	0.10 (2.54 max)	-	0.250 (6.35) min	0.093 ±0.005 (2.36 ± 0.13)	0.004 ± 0.001 (0.10 ± 0.13)

Note: “Non-Magnetic” means no magnetic materials.

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Electrical Specifications

Quality Factor (Q)	Greater than 10,000 at 1 MHz
Insulation Resistance (IR)	0.1pF to 470pF: 10^6 Megaohms min. @ +25°C rated WVDC 10^5 Megaohms min. @ +125°C rated WVDC 510pF to 1000pF: 10^5 Megaohms min. @ +25°C rated WVDC 10^4 Megaohms min. @ +125°C rated WVDC
Rated Voltage	See Rated Voltage Table
Dielectric Withstanding Voltage (WVDC)	250% of Rated Voltage of 5 seconds, Rated Voltage ≤ 500VDC 150% of Voltage for 5 seconds, 500VDC <Rated Voltage ≤ 1250 VDC 120% of Voltage for 5 seconds, Rated Voltage > 1250 VDC
Operating Temperature Range	-55°C to 200°C
Temperature Coefficient (TC)	C: -55°C to 125°C 0±30ppm/°C; >125°C to 200°C 0±60ppm/°C P: +90±20ppm/°C
Capacitance Drift	±0.02% or ±0.02pF, whichever is greater
Piezoelectric Effects	None
Termination Type	See Termination Type Table

Environmental Specifications

	Specification	Test Parameters
Thermal Shock	**DWV:** The initial Value **IR:** Shall not be less than 30% of the initial value. **Capacitance Change:** No more than 0.5% or 0.5pF, whichever is greater.	MIL-STD-202, Method 107, Condition A. At the maximum rated temperature (-55°C and 200°C) stay 30 minutes, the time of removing shall not be more than 3 minutes. Perform five cycles.
Moisture Resistance		MIL-STD-202, Method 106
Humidity (Steady State)	**DWV:** The initial Value **IR:** The initial value. **Capacitance Change:** No more than 0.3% or 0.3pF, whichever is greater.	MIL-STD-202, Method 103, Condition A With 1.5Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours minimum.
Life	**IR:** Shall not be less than 30% of the initial value. **Capacitance Change:** No more than 2.0% or 0.5pF, whichever is greater.	MIL-STD-202, Method 108. For 2000 hours, at 200°C. 200% of Voltage for Capacitors, Rated Voltage ≤ 500VDC; 120% of Voltage for Capacitors, 500VDC< Rated Voltage ≤1250VDC; 100% for Voltage for Capacitors, Rated Voltage >1250VDC
Terminal Strength	**Force:** 10lbs typical, 5lbs. Minimum. **Duration Time:** 5 to 10 seconds	MIL-STD-202, Method 211A, Test Condition A. Applied a force and maintained for a period of 5 to 10 seconds. The force shall be in the direction of the axes of the terminations.

Capacitors are designed and manufactured to meet the requirements of MIL-PRF-55681 and MIL-PRF-123.

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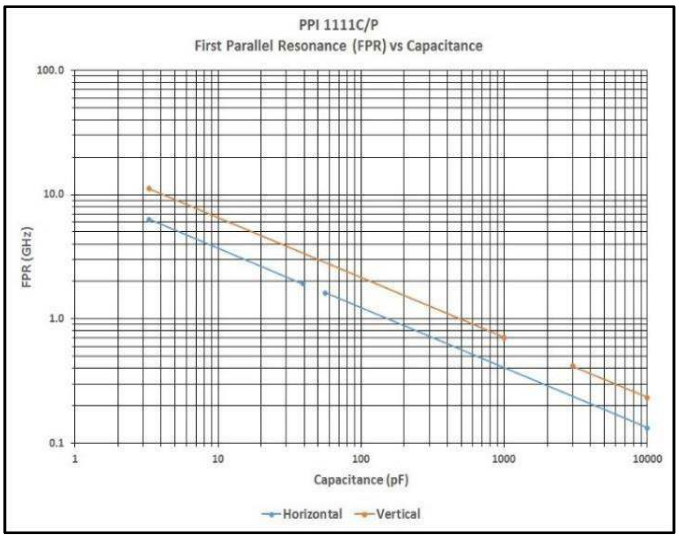
FPR -- First Parallel Resonance (FPRs)

Definitions and Measurement Conditions

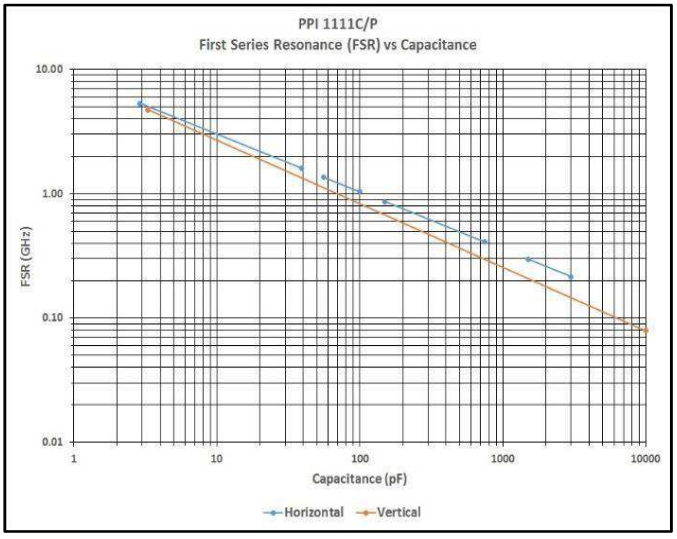
The **First Parallel Resonance, FPR,** is defined as the lowest frequency at which a suckout or notch appears in |S21|.
It is generally independent of substrate thickness or dielectric constant, but does depend on capacitor orientation. A horizontal orientation means the capacitor electrode planes are parallel to the plane of the substrate; a vertical orientation means the electrode planes are perpendicular to the substrate.



FSR -- First Series Resonance (FSRs)

Definitions and Measurement Conditions

The **First Series Resonance, FSR,** is defined as the lowest frequency at which the imaginary part of the input impedance, Im[Zin], equals zero. Should Im[Zin] or the real part of the input impedance, Re[Zin], not be monotonic with frequency at frequencies lower than those at which Im[Zin] =0, the FSR shall be considered as undefined (represented as a gap in the plot). FSR is dependent on internal capacitor structure; substrate thickness and dielectric constant; capacitor orientation, as defined alongside the FPR plot; and mounting pad dimensions.



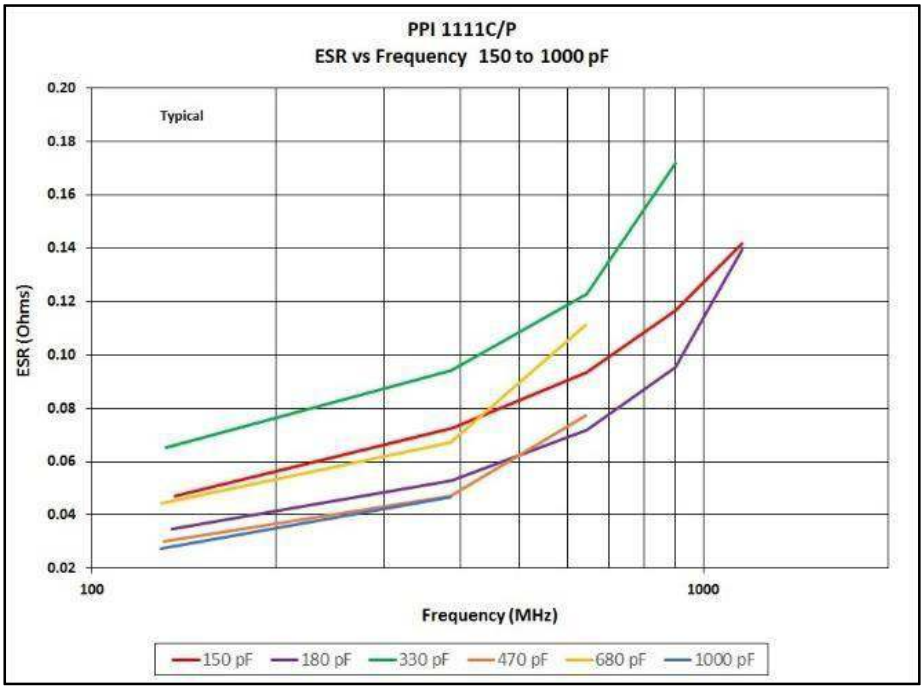
The measurement conditions are: substrate – Rogers RO4350; substrate dielectric constant = 3.66; horizontal mount substrate thickness (mils) = 50; gap in microstrip trace (mils) = 72; horizontal mount microstrip trace width (mils) = 110. Reference planes at sample edges.

All data has been derived from electrical models created by Modelithics, Inc., a specialty vendor contracted by PPI. The models are derived from measurements on a large number of parts disposed on several different substrates.

ESR vs. Frequency

1111C/P ESR vs Frequency

1111C ESR vs Frequency



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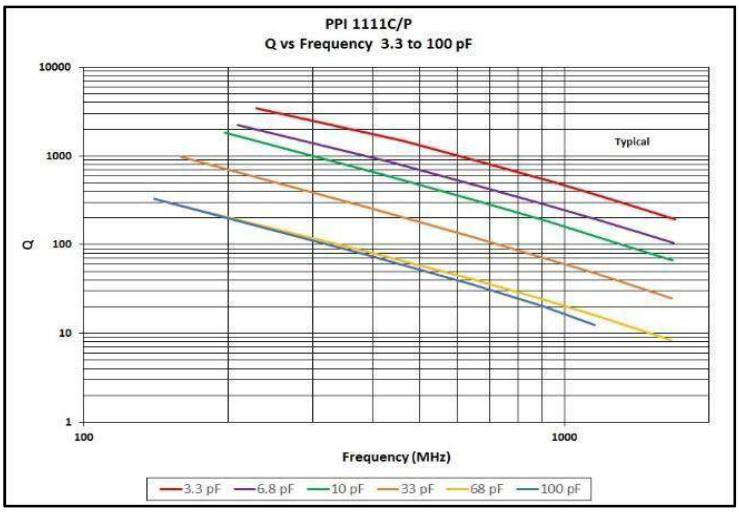
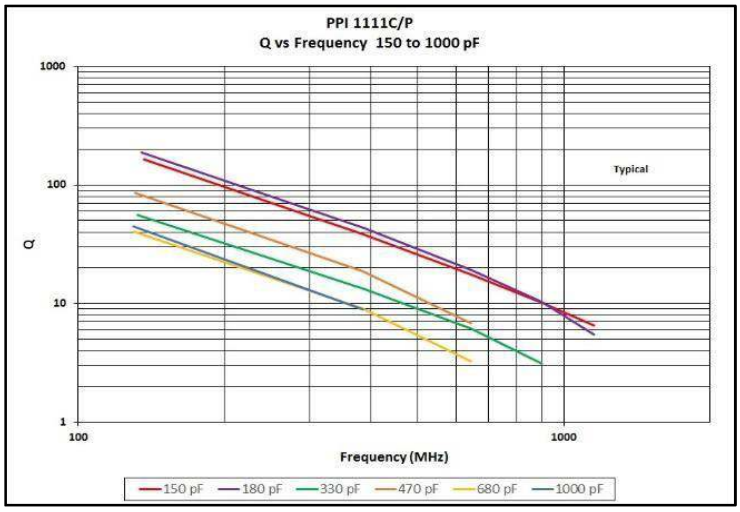
Q vs. Capacitance

1111C/P Q vs Frequency

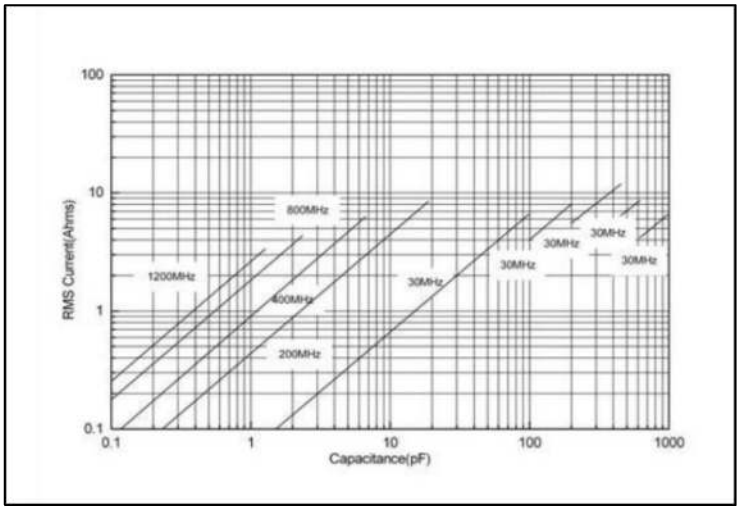


1111C Q vs Frequency

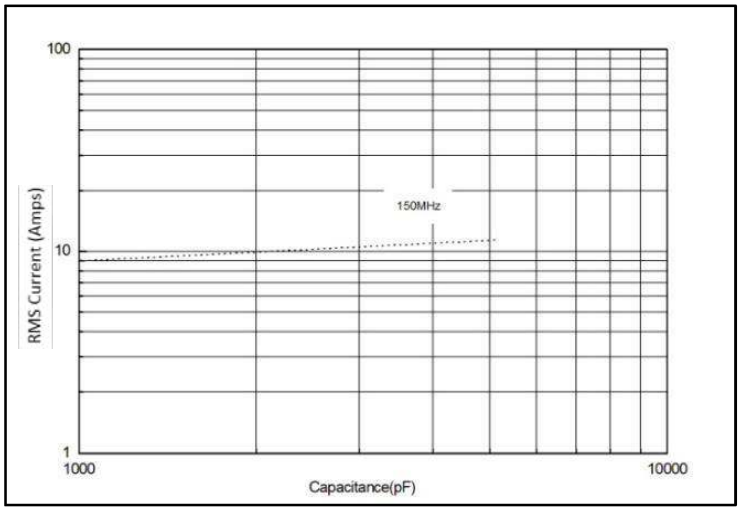


Current Rating vs. Capacitance

1111C/P Current Rating vs Capacitance



1111C Current Rating vs Capacitance



The current depends on voltage limited:

$$I = \frac{\sqrt{2}}{2} I_{peak} = \frac{\sqrt{2}}{2} \times \frac{V_{rated}}{X_C} = \sqrt{2}\pi f C V_{rated}$$

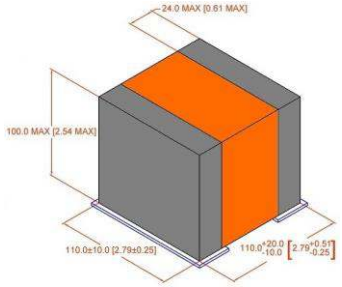
The current depends on power dissipation limited: $I = \sqrt{\frac{P_{dissipation}}{ESR}}$

Note: If the thermal resistance of mounting surface is 20°C/W. then a power dissipation of 3 W will result in the current limited we can calculate the current limited: $I = \sqrt{\frac{P_{dissipation}}{ESR}}$

1111C/P (0.110” x 0.110”)

Capacitor Application Program

Passive Plus, Inc.’s brand new **online Capacitor Application Program (**C.A.P.) helps Engineers and Designers select capacitors according to parameters such as cap value and frequency. C.A.P. allows engineers to insert capacitors requirements (Cap value, Frequency), producing Scattering Matrices (S2P) Charts while providing options (Case Size, Terminations, Mounting), and parameters (ESR, Q, Impedance) along with Datasheets. Once engineers have determined their capacitor requirements, C.A.P. also includes online Requests For Quotes (RFQs) and/or sample requests.



Modelithics Vendor Program

PPI offers design engineers a Free 90-Day Trial license for the Modelithics PPI Component Library. This program provides engineers access to extremely accurate scalable simulation models for Passive Plus capacitors with advanced features that enable a more precise and rapid design process.

Microwave Global Models include every part value in a series and permit users to input substrate thickness, dielectric constant, and loss tangent, as well as mounting pad layout dimensions. Selected models also include capacitor orientation – vertical or horizontal – as an input. Engineers can request FREE use of the models, by either visiting the Passive Plus Resources page (http://passiveplus.com/addldocs_resources.php).

1111C/P (0.110” x 0.110”)

Recommended Land Pattern Dimensions

When mounting the capacitor to substrate, it's important to carefully consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

1) The greater the amount of solder, the greater the stress to the elements. This may cause the substrate to break or crack.

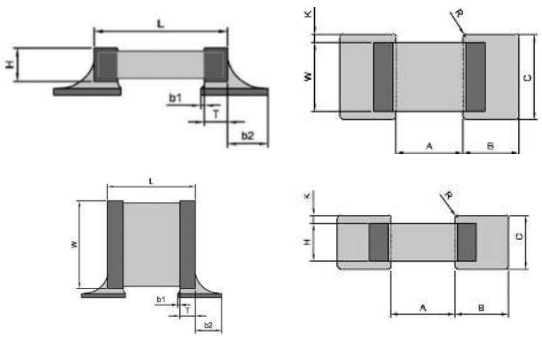
2) In the situation where two or more devices are mounted onto a common land, be sure to separate the device into exclusive pads by using soldering resist.

Horizontal Mounting (mm)

A	B	C
1.9	1.7	2.9

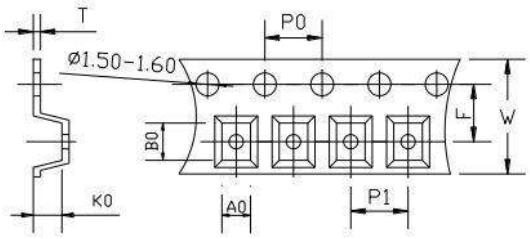
Vertical Mounting (mm)

A	B	C
1.9	1.7	2.5

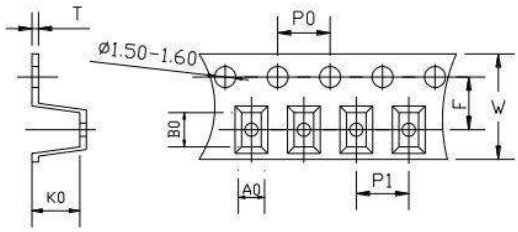


Tape & Reel Specifications (mm)

Horizontal Orientation



Vertical Orientation



Orientation	W	P0	P1	T	F	Qty Min	Qty/ reel	Tape Material
Horizontal	8.00	4.00	4.00	0.22	3.50	500	2000	Plastic
Vertical	12.00	4.00	4.00	0.40	5.50	500	1500	Plastic
Vertical	8.00	4.00	4.00	0.22	3.50	500	1500	Plastic

A_0 B_0 K_0

- Determined by component size. Typical clearance between the cavity and the component is:
  .05 (.002) min to .50 (.020) max for 8mm tape and .50 (.002) min to .65 (.026) max for 12mm tape.
- The component cannot rotate more than 20° within the determined cavity.

Dimensions: mm

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Engineering Design Kits

PPI offers Design Kits for engineers who are building and testing prototypes. Each kit contains 16 values;10 pieces per value.

Kits are offered in Magnetic or Non-Magnetic Terminations. Kits are 100% RoHS com liant.

Kit Number		Value Range	Values	
MAGNETIC	NON-MAGNETIC			
DKD1111C01 DKD1111P01	DKD1111C05 DKD1111P05	**1.0 - 10pF**	1.0, 1.2, 1.5, 1.8, 2.0, 2.2, 2.4, 2.7, 3.0, 3.3, 3.9, 4.7, 5.6, 6.8, 8.2, 10pF	RoHS
DKD1111C02 DKD1111P02	DKD1111C06 DKD1111P06	**10 - 100pF**	10, 12, 15, 18, 20, 22, 24, 27, 30, 33, 39, 47, 56, 68, 82, 100pF	RoHS
DKD1111C03 DKD1111P03	DKD1111C07 DKD1111P07	**100 - 1000pF**	100, 120, 150, 180, 200, 220, 240, 270, 300, 330, 390, 470, 560, 680, 820, 1000pF	RoHS
DKD1111C04 DKD1111P04	DKD1111C08 DKD1111P08	**1000 - 10000pF**	1000, 1100, 1200, 1500, 1800, 2000, 2200, 2700, 3000, 3300, 3900, 4700, 5100, 5600, 10000pF	RoHS